

Inventor: Scott T. Trosper

Title: "Electrical Interconnections, Methods of Conducting Electricity, and Methods of Reducing Horizontal Conductivity Within an Anisotropic Conductive Adhesive"

Assignee: Micron Technology, Inc.

RECEIVED  
JUL 27 2001  
OFFICE OF PETITIONS



**INFORMATION DISCLOSURE STATEMENT**  
**PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98**

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

Applicant encloses herewith copies of U.S. Patent No. 5,565,858 to Guthrie and U.S. Patent No. 5,450,070 to Massar et al. The other listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 09/364,249, filed July 29, 1999. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 7/26/01

By: 

James D. Shaurette  
Reg. No. 39,833  
WELLS, ST. JOHN, ROBERTS,  
GREGORY & MATKIN P.S.  
601 W. First Ave., Suite 1300  
Spokane, WA 99201-3828  
(509) 624-4276